

## THVD1330 具有 IEC ESD 保护功能的 32Mbps 3.3V RS485 收发器

## 1 特性

- 符合或超出 TIA/EIA-485A 标准要求
- 3 V 至 3.6 V 的电源电压
- 半双工 RS-422/RS-485
- 高速运行：32Mbps 最大数据速率
- 总线 I/O 保护
  - ±16kV HBM ESD
  - ±8kV IEC 61000-4-2 接触放电
- 工业级工作温度范围：-40°C 至 125°C
- 总线共模范围：-7 V 至 12V
- 低关断电流：5μA (最大值)
- 适用于热插拔功能的无干扰上电或断电
- 开路、短路和空闲总线失效防护接收器

## 2 应用

- 无线基础设施
- 工厂自动化与控制
- 楼宇自动化
- 电网基础设施

## 3 说明

THVD1330 是一款适用于工业应用的稳健半双工 RS-485 收发器。这些总线引脚可耐受高级别的 IEC 接触放电 ESD 事件，因此无需使用其他系统级保护元件。发射器和接收器都能够以最大 32Mbps 的信令速率运行。该器件进行了优化，可实现较小的传播延迟变化，以支持基带单元 (BBU) 和远程无线电单元 (RRU) 等时间敏感型应用。

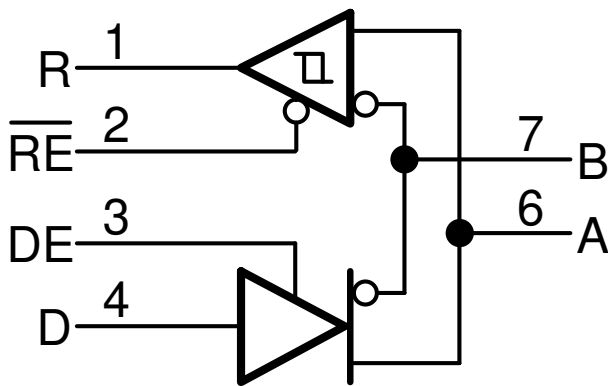
该器件由 3.3V 单电源供电。总线引脚具备宽共模电压范围和低输入泄漏，从而使 THVD1330 适用于长线缆上的多点应用。

THVD1330 采用可实现快插兼容性的业界通用 8 引脚 SOIC 封装。该器件的温度范围是 -40°C 至 125°C。

## 封装信息

器件型号	封装 <sup>(1)</sup>	封装尺寸 <sup>(2)</sup>
THVD1330	SOIC (D, 8)	4.9mm × 6mm

- 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
- 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。



简化版原理图



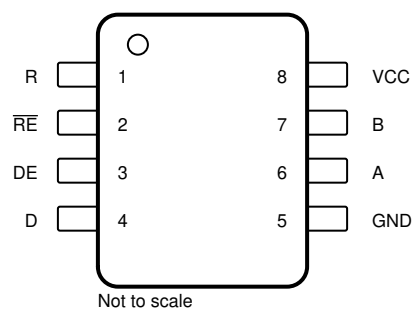
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## 4 Revision History

Date	Revision	Notes
September 2023	*	Initial release

## 5 Pin Configuration and Functions



**图 5-1. D Package, 8-Pin SOIC (Top View)**

**表 5-1. Pin Functions**

PIN		TYPE	DESCRIPTION
NAME	NO.		
R	1	Digital output	Receive data output
RE	2	Digital input	Receiver enable, active low (internal pull-up)
DE	3	Digital input	Driver enable, active high (internal pull-down)
D	4	Digital input	Driver data input
GND	5	Ground	Local device ground
A	6	Bus input/output	Bus I/O port, A (complementary to B)
B	7	Bus input/output	Bus I/O port, B (complementary to A)
V <sub>CC</sub>	8	Power	3.3 V supply

## 6 Specifications

### 6.1 Absolute Maximum Ratings

(1) (2)

		MIN	MAX	UNIT
Supply voltage	$V_{CC}$	- 0.3	6	V
Bus voltage	Voltage at any bus pin (A or B)	- 9	14	V
Input voltage	Voltage at any logic pin (D, DE or RE)	- 0.5	6	V
Receiver output current	$I_O$	- 11	11	mA
Junction temperature, $T_J$			170	°C
Storage temperature, $T_{stg}$		- 55	145	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values are with respect to Ground terminal

### 6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Contact discharge, per IEC61000-4-2	±8,000	V
		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±16,000	
		All pins except bus terminals and GND	±4,000	
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1,000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	3	3.3	3.6	V
$V_I$	Input voltage at any bus terminal (separately or common mode) <sup>(1)</sup>	- 7		12	V
$V_{IH}$	High-level input voltage (driver, driver enable, and receiver enable inputs)	2		$V_{CC}$	V
$V_{IL}$	Low-level input voltage (driver, driver enable, and receiver enable inputs)	0		0.8	V
$V_{ID}$	Differential input voltage	- 12		12	V
$I_O$	Output current, driver	- 60		60	mA
$I_{OR}$	Output current, receiver	- 8		8	mA
$R_L$	Differential load resistance	54	60		$\Omega$
$1/t_{UI}$	Signaling rate			32	Mbps
$T_A$	Operating ambient temperature	- 40		125	°C

- (1) The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

## 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		THVD1330	UNIT
		D (SOIC)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	116.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	56.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	63.4	°C/W
$\psi_{JT}$	Junction-to-top characterization parameter	8.8	°C/W
$\psi_{JB}$	Junction-to-board characterization parameter	62.6	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

over operating free-air temperature range, Typical values are at 25 °C and 3.3 V supply (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>Driver</b>						
$ V_{OD} $	Driver differential output voltage magnitude	$R_L = 60 \Omega$ , $-7 V \leq V_{test} \leq 12 V$ , See <a href="#">Figure 6-1</a>	1.5			V
		$R_L = 54 \Omega$ , See <a href="#">Figure 6-2</a>	1.5			V
		No load	2		3.6	V
$\Delta  V_{OD} $	Change in differential output voltage	$R_L = 54 \Omega$ , See <a href="#">Figure 6-2</a>	- 50		50	mV
$V_{OC}$	Common-mode output voltage	$R_L = 54 \Omega$ , See <a href="#">Figure 6-2</a>	1.4		2.5	V
$V_{OC(SS)}$	Change in steady-state common-mode output voltage	$R_L = 54 \Omega$ , See <a href="#">Figure 6-2</a>	- 50		50	mV
$V_{OC(pp)}$	Peak-to-peak common-mode output voltage	$R_L = 54 \Omega$ , $C_L = 50 pF$ , $PRR = 500 kHz$ , See <a href="#">Figure 6-2</a>		400		mV
$I_{OS}$	Short-circuit output current	$DE = V_{CC}$ , $-7 V < V_O < 12 V$ , Voltage applied on one bus line with other bus line floating	- 250		250	mA
$C_{OD}$	Differential output capacitance	$V_I = 0.4 \sin(4E6 \pi t) + 0.5 V$ , $DE = 0$		16		pF
<b>Receiver</b>						
$I_I$	Bus input current	$V_{CC} = 3.6 V$	$V_I = 12 V$	200	500	$\mu A$
			$V_I = -7 V$	- 400	- 200	
		$V_{CC} = 0 V$	$V_I = 12 V$	250	500	
			$V_I = -7 V$	- 400	- 150	
$V_{TH+}$	Positive-going input-threshold voltage <sup>(1)</sup>	Over common-mode range of (+12V,-7V)		- 75	- 20	mV
$V_{TH-}$	Negative-going input-threshold voltage <sup>(1)</sup>			- 200	- 125	mV
$V_{HYS}$	Input hysteresis			50		mV
$V_{OH}$	Output high voltage	$I_{OH} = -8 mA$	2.4			V
$V_{OL}$	Output low voltage	$I_{OL} = 8 mA$			0.4	V
$I_{OZ}$	Output high-impedance current	$V_O = 0 V$ or $V_{CC}$ , $RE = V_{CC}$	- 1		1	$\mu A$
$C_{ID}$	Differential input capacitance	$V_I = 0.4 \sin(4E6 \pi t) + 0.5 V$ , $DE = 0$		15		pF

## 6.5 Electrical Characteristics (续)

over operating free-air temperature range, Typical values are at 25 °C and 3.3 V supply (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Logic							
I <sub>IN</sub>	Input current DE	V <sub>IN</sub> = 5V		0		100	μA
	Input current DE	V <sub>IN</sub> = 0V		0		100	μA
	Input current D	V <sub>IN</sub> = 5V		- 100		0	μA
	Input current D	V <sub>IN</sub> = 0V		- 100		0	μA
	Input current ( $\overline{RE}$ )	V <sub>IN</sub> = 2V		- 30		0	μA
		V <sub>IN</sub> = 0.8V		- 30		0	μA
Thermal Protection							
T <sub>SHDN</sub>	Thermal shutdown threshold	Temperature rising		150	170		°C
T <sub>HYS</sub>	Thermal shutdown hysteresis				10		°C
Supply							
I <sub>CC</sub>	Supply current (quiescent)	Driver and receiver enabled	$\overline{RE}$ = 0 V, DE = V <sub>CC</sub> , No load			2	mA
		Driver enabled, receiver disabled	$\overline{RE}$ = V <sub>CC</sub> , DE = V <sub>CC</sub> , No load			1.5	mA
		Driver disabled, receiver enabled	$\overline{RE}$ = 0 V, DE = 0 V, No load			1.5	mA
		Driver and receiver disabled	$\overline{RE}$ = V <sub>CC</sub> , DE = 0 V, D = V <sub>CC</sub> , No load			5	μA

(1) Under any specific conditions,  $V_{TH+}$  is assured to be at least  $V_{HYS}$  higher than  $V_{TH-}$ .

## 6.6 Switching Characteristics

Over recommended operating conditions

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Driver: 32Mbps							
t <sub>r</sub> , t <sub>f</sub>	Differential output rise/fall time	R <sub>L</sub> = 54 Ω , C <sub>L</sub> = 50 pF, PRR=500KHz, Across full range of process, voltage and temperature	See Figure 6-3	3	4.5	10	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation delay			5	8.5	16	ns
t <sub>SK(P)</sub>	Pulse skew,  t <sub>PHL</sub> - t <sub>PLH</sub>					1.5	ns
t <sub>SK(PP)</sub>	Part to part skew					6	ns
t <sub>PHL</sub> , t <sub>PLH</sub>	Propagation delay	R <sub>L</sub> = 54 Ω , C <sub>L</sub> = 50pF, V <sub>CC</sub> = 3.3 V +/- 3%, T <sub>A</sub> = -20°C to 85°C		6		13.8	ns
t <sub>PHZ</sub>	Disable time	PRR = 500KHz, R <sub>L</sub> = 110 Ω , C <sub>L</sub> = 50 pF	See Figure 6-4 and Figure 6-5			25	ns
t <sub>PLZ</sub>	Disable time	PRR = 500KHz, R <sub>L</sub> = 110 Ω , C <sub>L</sub> = 50 pF				26	ns
t <sub>PZH</sub>	Enable time	RE = 0 V, PRR = 500KHz, R <sub>L</sub> = 110 Ω , C <sub>L</sub> = 50 pF				31	ns
t <sub>PZL</sub>					26	ns	
t <sub>PZH2</sub>	Enable time	RE = V <sub>CC</sub> , PRR = 100KHz, R <sub>L</sub> = 110 Ω ± 1%, C <sub>L</sub> = 50 pF ± 20%, 50% to 2.3V				6	μs
t <sub>PZL2</sub>					6	μs	
Receiver: 32Mbps							

## 6.6 Switching Characteristics (续)

Over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_r, t_f$	Differential output rise/fall time	PRR = 500KHz, $C_L = 15\text{pF}$ , Across process, full range of voltage and ambient temperature	1	2	5	ns
$t_{PHL}, t_{PLH}$	Propagation delay		12.5	20	25	ns
$t_{SK(P)}$	Pulse skew, $ t_{PHL} - t_{PLH} $				1.5	ns
$t_{SK(PP)}$	Part to part skew				8	ns
$t_{PHL}, t_{PLH}$	Propagation delay	PRR = 500KHz, $C_L = 15\text{pF}$ , $V_{CC} = 3.3\text{V} \pm 3\%$ , $T_A = -20^\circ\text{C}$ to $85^\circ\text{C}$	13		20	ns
$t_{PHL}, t_{PLH}$	Propagation delay	PRR = 500KHz, $C_L = 30\text{pF}$ , $V_{CC} = 3.3\text{V} \pm 3\%$ , $T_A = -20^\circ\text{C}$ to $85^\circ\text{C}$	13.4		21	ns
$t_{PHZ}$	Output disable time from high-level	PRR = 500KHz, $C_L = 15\text{pF}$			20	ns
$t_{PLZ}$	Output disable time from low-level	PRR = 500KHz, $C_L = 15\text{pF}$			15	ns
$t_{PZH}$	Output enable time to high-level	DE = $V_{CC}$ , PRR = 500KHz, $C_L = 15\text{pF}$			15	ns
$t_{PZL}$	Output enable time to low-level				15	ns
$t_{PZH2}$	Output enable time to high-level				6	$\mu\text{s}$
$t_{PZL2}$	Output enable time to low-level				6	$\mu\text{s}$

## 6.7 Typical Characteristics

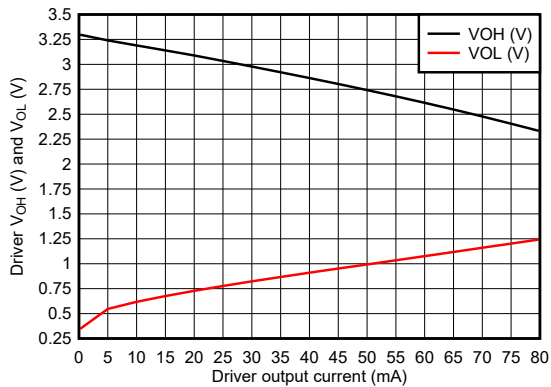


图 6-1. Driver Output voltage vs Driver Output Current

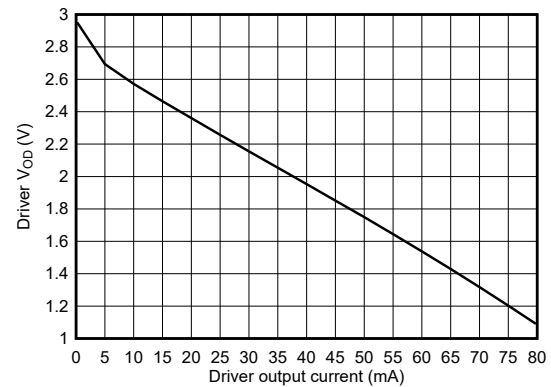


图 6-2. Driver Differential Output voltage vs Driver Output Current

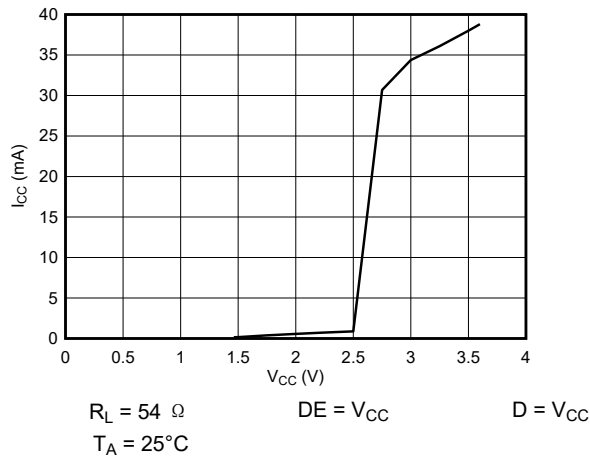


图 6-3. Supply Current vs Supply Voltage

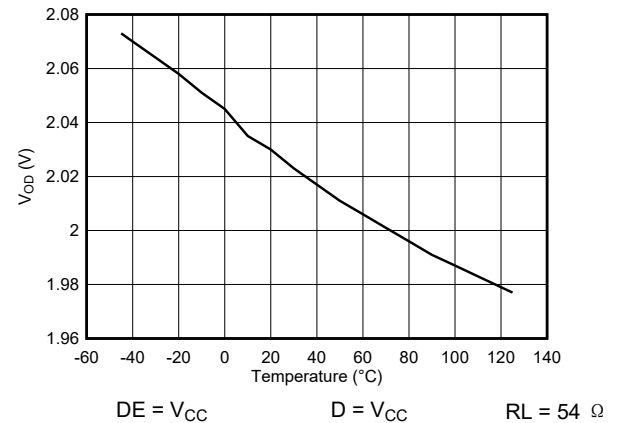


图 6-4. Driver output differential voltage vs Temperature

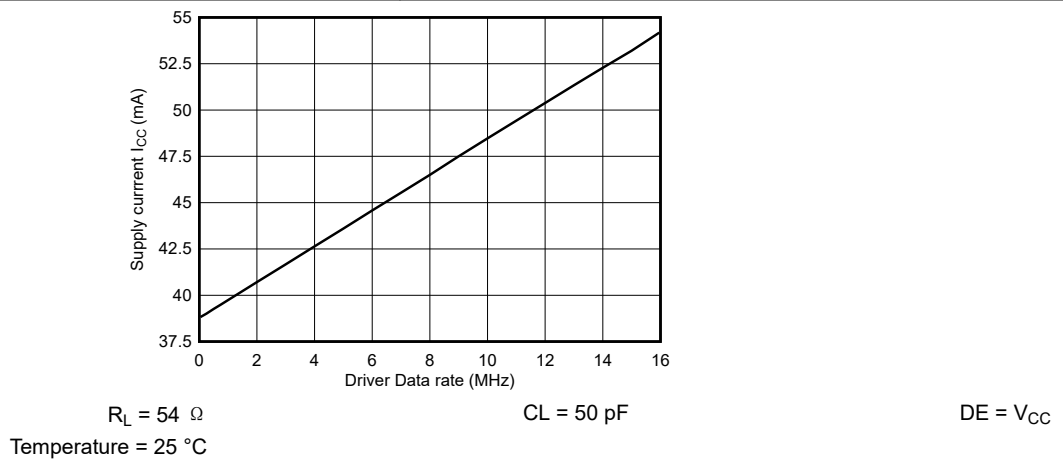
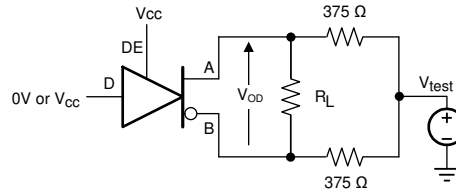


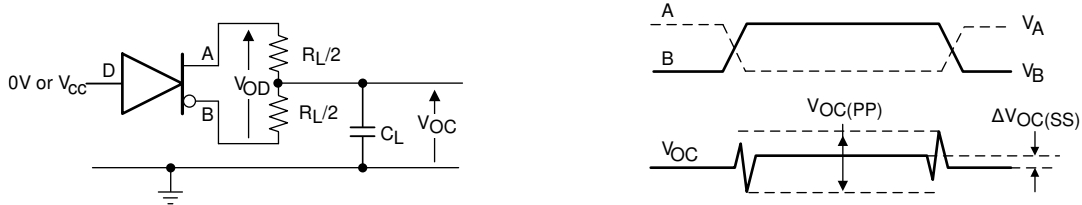
图 6-5. Supply Current vs Signal Rate



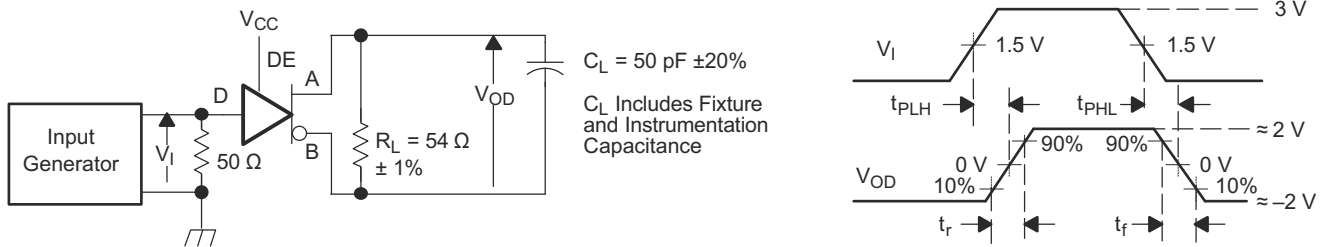
## 7 Parameter Measurement Information



**图 7-1. Measurement of Driver Differential Output Voltage With Common-Mode Load**



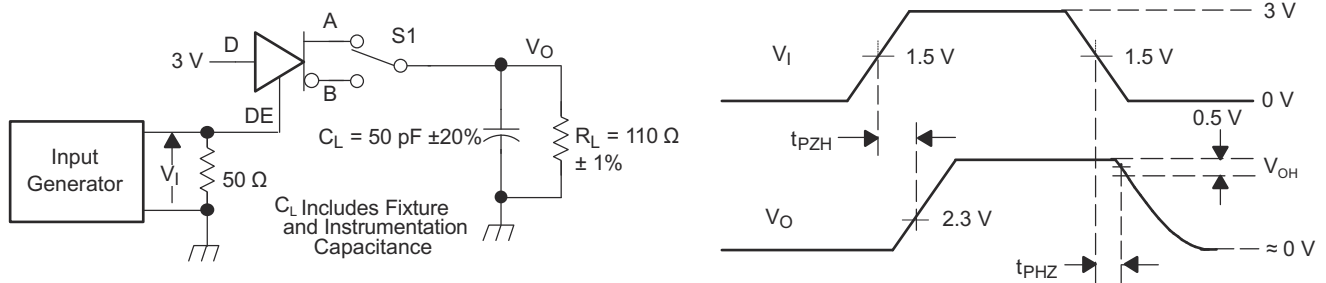
**图 7-2. Measurement of Driver Differential and Common-Mode Output With RS-485 Load**



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Generator: PRR = 500 kHz, 50% Duty Cycle,  $t_r < 60$  ns,  $t_f < 6$  ns  $Z_0 = 50 \Omega$

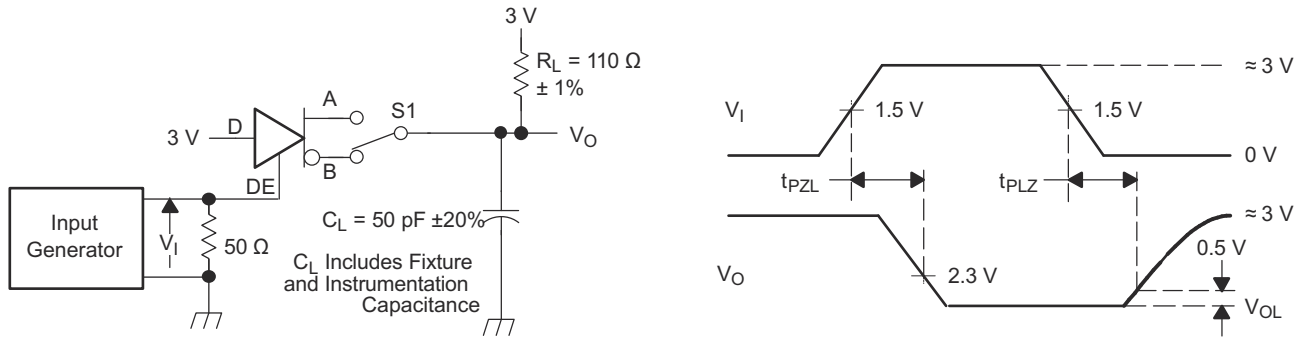
**图 7-3. Driver Switching Test Circuit and Voltage Waveforms**



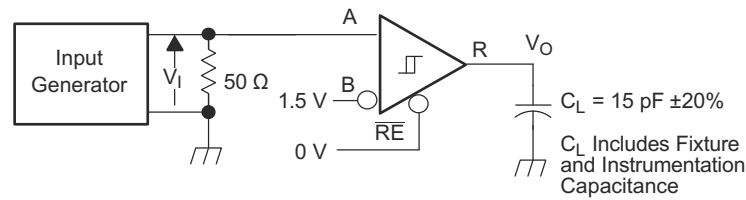
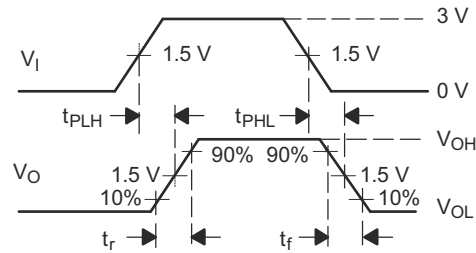
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Generator: PRR = 500 kHz, 50% Duty Cycle,  $t_r < 60$  ns,  $t_f < 6$  ns  $Z_0 = 50 \Omega$

**图 7-4. Driver High-Level Enable and Disable Time Test Circuit and Voltage Waveforms**

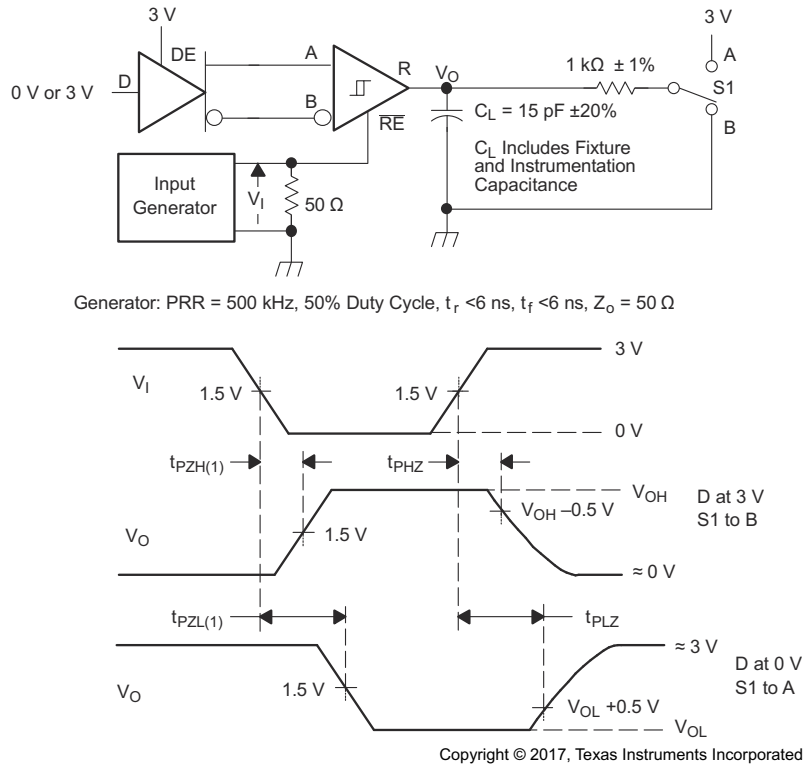


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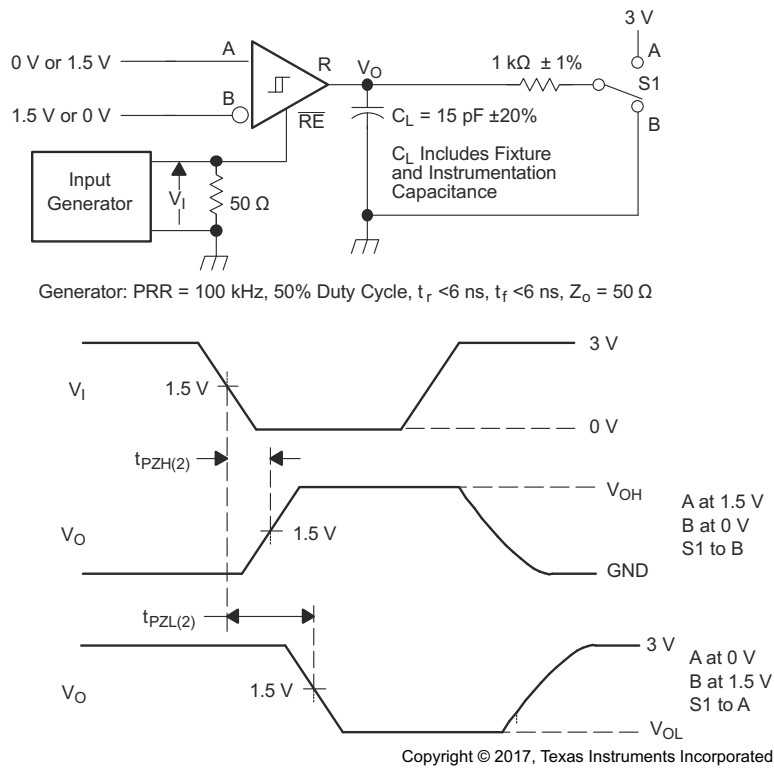
Generator: PRR = 500 kHz, 50% Duty Cycle,  $t_r < 60$  ns,  $t_f < 6$  ns  $Z_O = 50 \Omega$ **图 7-5. Driver Low-Level Output Enable and Disable Time Test Circuit and Voltage Waveforms**Generator: PRR = 500 kHz, 50% Duty Cycle,  $t_r < 6$  ns,  $t_f < 6$  ns,  $Z_O = 50 \Omega$ 

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**图 7-6. Receiver Switching Test Circuit and Voltage Waveforms**



**图 7-7. Receiver Enable and Disable Time Test Circuit and Voltage Waveforms With Drivers Enabled**



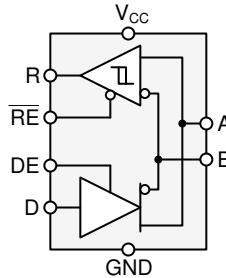
**图 7-8. Receiver Enable Time From Standby (Driver Disabled)**

## 8 Detailed Description

### 8.1 Overview

The THVD1330 is a low-power, half-duplex RS-485 transceiver suitable for data transmission up to 32 Mbps. This device has active-high driver enable and active-low receiver enable. Disabling both driver and receiver can achieve a standby current of less than 5  $\mu$ A.

### 8.2 功能方框图



### 8.3 Feature Description

Internal ESD protection circuits protect the transceiver against Electrostatic Discharges (ESD) according to IEC 61000-4-2 of up to  $\pm 8$  kV (Contact Discharge).

The THVD1330 provides internal biasing of the receiver input thresholds in combination with large input-threshold hysteresis. With a input hysteresis (typical) of  $V_{HYS} = 50$  mV, the receiver output remains logic high under a bus-idle or bus-short conditions without the need for external failsafe biasing resistors. Device operation is specified over a wide temperature range from  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

### 8.4 Device Functional Modes

When the driver enable pin, DE, is logic high, the differential outputs A and B follow the logic states at data input D. A logic high at D causes A to turn high and B to turn low. In this case, the differential output voltage defined as  $V_{OD} = V_A - V_B$  is positive. When D is low, the output states reverse, B turns high, A becomes low, and  $V_{OD}$  is negative.

When DE is low, both outputs turn high-impedance. In this condition the logic state at D is irrelevant. The DE pin has an internal pull-down resistor to ground, thus when left open the driver is disabled (high-impedance) by default. The D pin has an internal pull-up resistor to  $V_{CC}$ , thus, when left open while the driver is enabled, output A turns high and B turns low.

表 8-1. Driver Function Table

INPUT D	ENABLE DE	OUTPUTS		FUNCTION
		A	B	
H	H	H	L	Actively drive bus high
L	H	L	H	Actively drive bus low
X	L	Z	Z	Driver disabled
X	OPEN	Z	Z	Driver disabled by default
OPEN	H	H	L	Actively drive bus high by default

When the receiver enable pin,  $\overline{\text{RE}}$ , is logic low, the receiver is enabled. When the differential input voltage defined as  $V_{ID} = V_A - V_B$  is positive and higher than the positive input threshold,  $V_{IT+}$ , the receiver output, R, turns high. When  $V_{ID}$  is negative and lower than the negative input threshold,  $V_{IT-}$ , the receiver output, R, turns low. If  $V_{ID}$  is between  $V_{IT+}$  and  $V_{IT-}$  the output is indeterminate.

When  $\overline{\text{RE}}$  is logic high or left open, the receiver output is high-impedance and the magnitude and polarity of  $V_{ID}$  are irrelevant. Internal biasing of the receiver inputs causes the output to go failsafe-high when the transceiver is

disconnected from the bus (open-circuit), the bus lines are shorted (short-circuit), or the bus is not actively driven (idle bus).

**表 8-2. Receiver Function Table**

DIFFERENTIAL INPUT	ENABLE	OUTPUT	FUNCTION
$V_{ID} = V_A - V_B$	RE	R	
$V_{IT+} < V_{ID}$	L	H	Receive valid bus high
$V_{IT-} < V_{ID} < V_{IT+}$	L	?	Indeterminate bus state
$V_{ID} < V_{IT-}$	L	L	Receive valid bus low
X	H	Z	Receiver disabled
X	OPEN	Z	Receiver disabled by default
Open-circuit bus	L	H	Fail-safe high output
Short-circuit bus	L	H	Fail-safe high output
Idle (terminated) bus	L	H	Fail-safe high output

## 9 Application and Implementation

### 备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The THVD1330 is a half-duplex RS-485 transceiver commonly used for asynchronous data transmissions. The driver and receiver enable pins allow for the configuration of different operating modes.

- Using independent enable lines provides the most flexible control as it allows for the driver and the receiver to be turned on and off individually. While this configuration requires two control lines, it allows for selective listening into the bus traffic, whether the driver is transmitting data or not.
- Combining the enable signals simplifies the interface to the controller by forming a single direction-control signal. In this configuration, the transceiver operates as a driver when the direction-control line is high, and as a receiver when the direction-control line is low.
- Only one line is required when connecting the receiver-enable input to ground and controlling only the driver-enable input. In this configuration, a node not only receives the data from the bus, but also the data it sends and can verify that the correct data have been transmitted.

### 9.2 Typical Application

An RS-485 bus consists of multiple transceivers connecting in parallel to a bus cable. To eliminate line reflections, each cable end is terminated with a termination resistor,  $R_T$ , whose value matches the characteristic impedance,  $Z_0$ , of the cable. This method, known as parallel termination, allows for higher data rates over longer cable length.

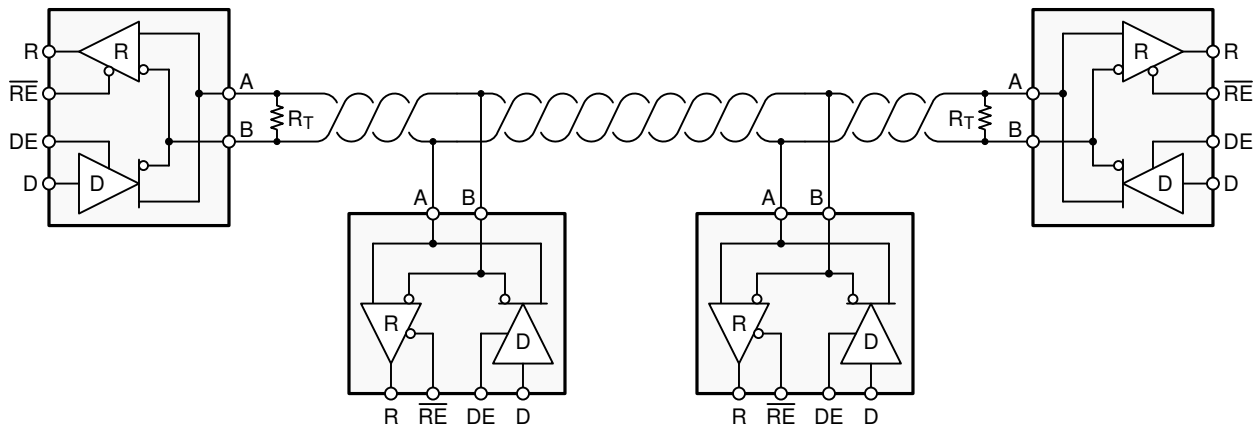


图 9-1. Typical RS-485 Network With Half-Duplex Transceivers

#### 9.2.1 Design Requirements

RS-485 is a robust electrical standard suitable for long-distance networking that is used in a wide range of applications with varying requirements, such as distance, data rate, and number of nodes.

##### 9.2.1.1 Data Rate and Bus Length

There is an inverse relationship between data rate and cable length, which means the higher the data rate, the shorter the cable length; and conversely, the lower the data rate, the longer the cable length. While most RS-485 systems use data rates between 10 kbps and 100 kbps, some applications require data rates up to 300 kbps at

distances of 4000 feet and longer. Longer distances are possible by allowing for small signal jitter of up to 5 or 10%.

### 9.2.1.2 Stub Length

When connecting a node to the bus, the distance between the transceiver inputs and the cable trunk, known as the stub, must be as short as possible. Stubs present a non-terminated piece of bus line which can introduce reflections as the length of the stub increases. As a general guideline, the electrical length, or round-trip delay, of a stub is less than one-tenth of the rise time of the driver, thus giving a maximum physical stub length as shown in [方程式 1](#).

$$L_{(STUB)} \leq 0.1 \times t_r \times v \times c \quad (1)$$

where

- $t_r$  is the 10/90 rise time of the driver
- $c$  is the speed of light ( $3 \times 10^8$  m/s)
- $v$  is the signal velocity of the cable or trace as a factor of  $c$

### 9.2.1.3 Bus Loading

The RS-485 standard specifies that a compliant driver must be able to driver 32 unit loads (UL), where 1 unit load represents a load impedance of approximately 12 k $\Omega$ . Connecting up to 64 receivers to the bus is possible because the THVD1330 consists of 1/2 UL transceivers.

### 9.2.1.4 Receiver Failsafe

The differential receivers of the THVD1330 are *failsafe* to invalid bus states caused by the following:

- Open bus conditions, such as a disconnected connector
- Shorted bus conditions, such as cable damage shorting the twisted-pair together
- Idle bus conditions that occur when no driver on the bus is actively driving

In any of these cases, the differential receiver output a failsafe logic high state so that the output of the receiver is not indeterminate.

Receiver failsafe is accomplished by offsetting the receiver thresholds such that the *input indeterminate* range does not include zero volts differential. To comply with the RS-422 and RS-485 standards, the receiver output must output a high when the differential input  $V_{ID}$  is more positive than 200 mV, and must output a low when  $V_{ID}$  is less than  $-200$  mV. The receiver parameters which determine the failsafe performance are  $V_{IT+}$ ,  $V_{IT-}$ , and  $V_{HYS}$  (the separation between  $V_{IT+}$  and  $V_{IT-}$ ). As shown in the [Table 7-2](#), differential signals less than  $-200$  mV always cause a low receiver output. Differential signals greater than 200 mV always cause a high receiver output.

When the differential input signal is close to zero, it is still above the  $V_{IT+}$  threshold, and the receiver output is high. Only when the differential input is more than  $V_{HYS}$  below  $V_{IT+}$  does the receiver output transition to a low state. Therefore, the noise immunity of the receiver inputs during a bus fault conditions includes the receiver hysteresis value,  $V_{HYS}$ , as well as the value of  $V_{IT+}$ .



### 9.2.1.5 Transient Protection

The bus pins of the THVD1330 transceiver family include on-chip ESD protection against  $\pm 16$ -kV HBM and  $\pm 8$ -kV IEC 61000-4-2 contact discharge. The International Electrotechnical Commission (IEC) ESD test is far more severe than the HBM ESD test. The 50% higher charge capacitance,  $C_{(S)}$ , and 78% lower discharge resistance,  $R_{(D)}$ , of the IEC model produce significantly higher discharge currents than the HBM model.

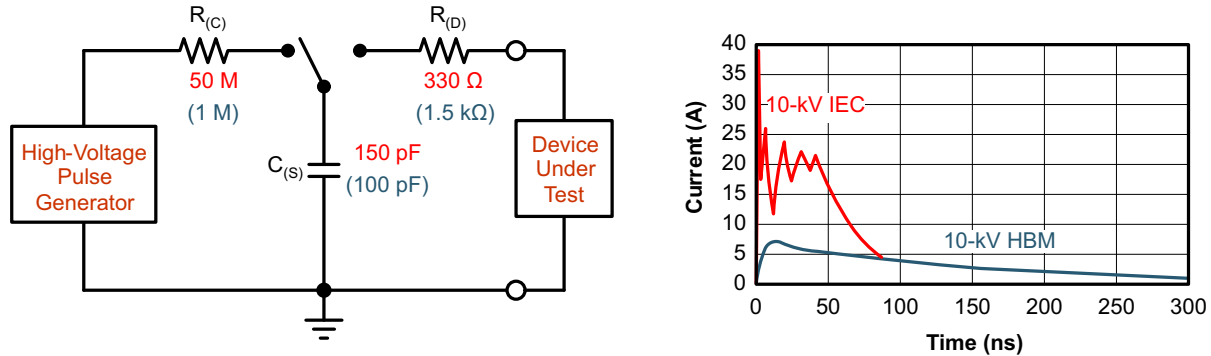


图 9-2. HBM and IEC ESD Models and Currents in Comparison (HBM Values in Parenthesis)

The on-chip implementation of IEC ESD protection significantly increases the robustness of equipment. Common discharge events occur because of human contact with connectors and cables. Designers can choose to implement protection against longer duration transients, typically referred to as surge transients.

### 9.2.2 Detailed Design Procedure

To protect bus nodes against high-energy transients, the implementation of external transient protection devices is necessary. 图 9-3 suggest a protection circuit against 1 kV surge (IEC 61000-4-5) transients. 表 9-1 shows the associated Bill of Materials.

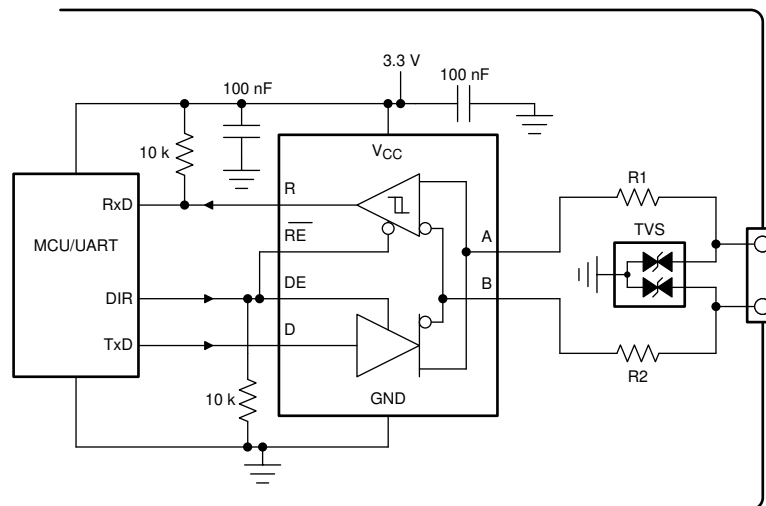


图 9-3. Transient Protection Against ESD, EFT, and Surge Transients for Half-Duplex Devices

表 9-1. Bill of Materials

DEVICE	FUNCTION	ORDER NUMBER	MANUFACTURER <sup>(1)</sup>
XCVR	RS-485 transceiver	THVD1330	TI
R1	10-Ω, pulse-proof thick-film resistor	CRCW0603010RJNEAHP	Vishay
R2			

表 9-1. Bill of Materials (续)

DEVICE	FUNCTION	ORDER NUMBER	MANUFACTURER <sup>(1)</sup>
TVS	Bidirectional 400-W transient suppressor	CDSOT23-SM712	Bourns

(1) See the [Third-Party Products Disclaimer](#).

### 9.2.3 Application Curves

图 9-4 shows typical supply current consumption of the device at 54  $\Omega$  load and 50 pF load capacitor with driver enabled and data is toggled at varying data rates.

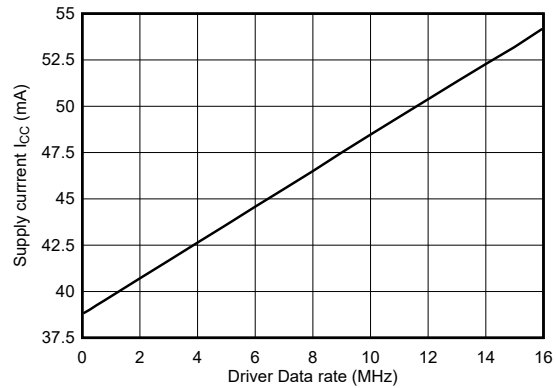


图 9-4. Supply Current vs Signal Rate

### 9.3 Power Supply Recommendations

For reliable operation at all data rates and supply voltages, each supply is decoupled with a 100 nF ceramic capacitor located as close as possible to the supply pins. This helps reduce supply voltage ripple present on the outputs of switched-mode power supplies. This also helps to compensate for the resistance and inductance of the PCB power planes.

## 9.4 Layout

### 9.4.1 Layout Guidelines

Robust and reliable bus node design often requires the use of external transient protection devices to protect against surge transients that occurs in industrial environments. Since these transients have a wide frequency bandwidth (from approximately 3 MHz to 300 MHz), high-frequency layout techniques are applied during PCB design.

1. Place the protection circuitry close to the bus connector to prevent noise transients from propagating across the board.
2. Use  $V_{CC}$  and ground planes to provide low inductance. Note that high-frequency currents tend to follow the path of least impedance and not the path of least resistance.
3. Design the protection components into the direction of the signal path. Do not force the transient currents to divert from the signal path to reach the protection device.
4. Apply 100-nF to 220-nF bypass capacitors as close as possible to the  $V_{CC}$  pins of transceiver, UART and controller ICs on the board.
5. Use at least two vias for  $V_{CC}$  and ground connections of bypass capacitors and protection devices to minimize effective via inductance.
6. Use 1-k $\Omega$  to 10-k $\Omega$  pullup and pulldown resistors for enable lines to limit noise currents in these lines during transient events.
7. Insert pulse-proof resistors into the A and B bus lines if the TVS clamping voltage is higher than the specified maximum voltage of the transceiver bus pins. These resistors limit the residual clamping current into the transceiver and prevent it from latching up.
8. While pure TVS protection is sufficient for surge transients up to 1 kV, higher transients require metal-oxide varistors (MOVs) which reduce the transients to a few hundred volts of clamping voltage, and transient blocking units (TBUs) that limit transient current to less than 1 mA.

### 9.4.2 Layout Example

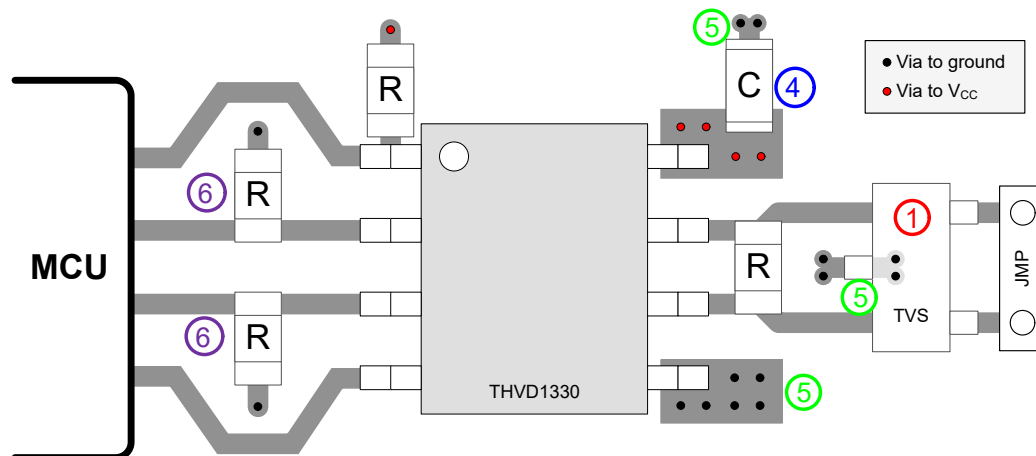


图 9-5. Layout Example

## 10 Device and Documentation Support

### 10.1 第三方产品免责声明

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### 10.2 Device Support

### 10.3 接收文档更新通知

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### 10.4 支持资源

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### 10.7 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">THVD1330DR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	T1330
THVD1330DR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	T1330

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**D0008A**

# PACKAGE OUTLINE

**SOIC - 1.75 mm max height**

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

## NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

**D0008A**

## SOIC - 1.75 mm max height

## SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



## SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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